

## OSG65R760x\_Datasheet



# Enhancement Mode N-Channel Power MOSFET

## Features

- ◆ Low  $R_{DS(on)}$
- ◆ Low FOM
- ◆ Extremely low switching loss
- ◆ Good stability and uniformity
- ◆ Advanced GreenMOS™ technology

## Applications

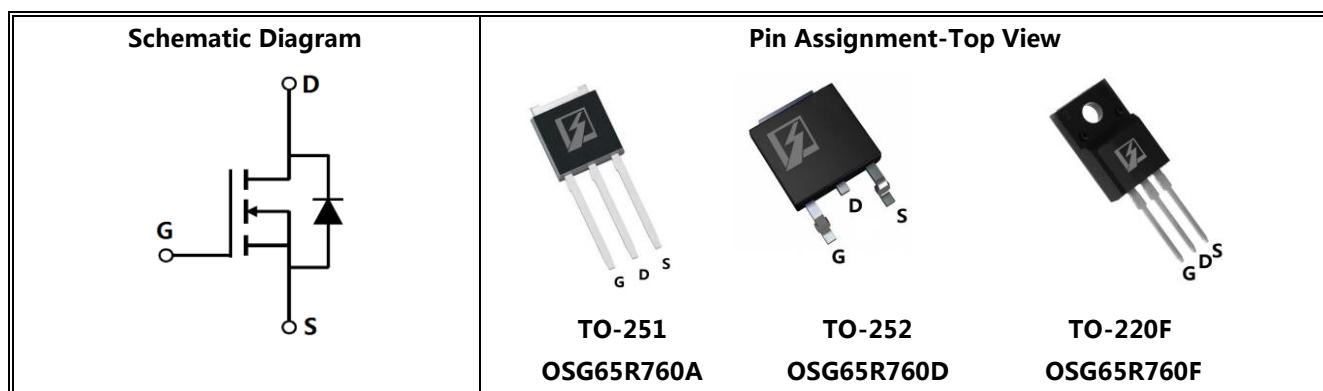
- ◆ Consumer electronics power supply
- ◆ LCD/LED/PDP
- ◆ Portable digital power management
- ◆ PFC
- ◆ Charger

## ■ General Description

OSG65R760x series use advanced GreenMOS™ technology to provide low  $R_{DS(ON)}$ , low gate charge, fast switching and excellent avalanche characteristics. This device is suitable for active power factor correction and switching mode power supply applications.

- ◆  $V_{DS@Tjmax}$  700V
- ◆  $I_D$  7A
- ◆  $R_{DS(ON),max}@V_{GS}=10V$  0.76Ω

## ■ TO-251,TO-252,TO-220F Package Information



## ■ Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted )

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	650	V
Gate-Source Voltage	$V_{GS}$	$\pm 30$	V
Drain Current-Continuous <sup>(Note 1)</sup>	$I_D$	7	A
Drain Current- Pulsed <sup>(Note 2)</sup>	$I_{DM}$	21	A
Power Dissipation <sup>(Note 3)</sup> for TO-251,TO-252	$P_D$	37	W
Power Dissipation <sup>(Note 3)</sup> for TO-220F		26	
Single Pulsed-Avalanche Energy <sup>(Note 6)</sup>	$E_{AS}$	136	mJ
Operation and Storage Junction Temperature	$T_{STG}, T_J$	-55 to 150	°C

## ■ Thermal Characteristics

Parameter	Symbol	Value		Unit
		TO251/TO252	TO220F	
Thermal Resistance, Junction-to-Case	R <sub>θJC</sub>	3.38	4.8	°C/W
Thermal Resistance, Junction-to-Ambient <sup>(Note 4)</sup>	R <sub>θJA</sub>	62	80	°C/W

## ■ Electrical Characteristics ( T<sub>A</sub>=25°C unless otherwise noted )

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	650			V	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA
		700	771			V <sub>GS</sub> =0V, I <sub>D</sub> =250μA, T <sub>j</sub> =150°C
Gate Threshold Voltage	V <sub>GS(th)</sub>	2.0		4.0	V	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA
Drain-Source On-state Resistance	R <sub>DS(ON)</sub>		0.66	0.76	Ω	V <sub>GS</sub> =10V, I <sub>D</sub> =3A
			1.58			V <sub>GS</sub> =10V, I <sub>D</sub> =3A, T <sub>j</sub> =150°C
Gate-Source Leakage Current	I <sub>GSS</sub>			100	nA	V <sub>GS</sub> =30V
				-100		V <sub>GS</sub> =-30V
Drain-to-Source leakage current	I <sub>DSS</sub>			1	μA	V <sub>DS</sub> =650V, V <sub>GS</sub> =0V

## ■ Dynamic Characteristics

Input Capacitance	C <sub>iss</sub>		343		pF	V <sub>GS</sub> =0V, V <sub>DS</sub> =50V, f=1MHZ
Output Capacitance	C <sub>oss</sub>		29		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>		1.5		pF	
Turn-on Delay Time	t <sub>d(on)</sub>		15		ns	V <sub>GS</sub> =10V, V <sub>DS</sub> =380V, R <sub>G</sub> =25Ω I <sub>D</sub> =7A
Turn-on Rise Time	t <sub>r</sub>		11		ns	
Turn-Off Delay Time	t <sub>d(off)</sub>		23		ns	
Turn-Off Fall Time	t <sub>f</sub>		22		ns	

## ■ Gate Charge Characteristics

Total Gate Charge	$Q_g$		8.7		nC	$I_D=7A$ , $V_{DS}=480V$ , $V_{GS}=10V$
Gate-Source Charge	$Q_{gs}$		2.4		nC	
Gate-Drain Charge	$Q_{gd}$		3.5		nC	

## ■ Body Diode Characteristics

Body-diode Forward Current <sup>(NOTE 2)</sup>	$I_S$			7	A	$V_{GS} < V_{th}$
Pulsed Source Current	$I_{SP}$			21		
Inverse Diode Forward Voltage	$V_{SD}$			1.3	V	$I_S=7A, V_{GS}=0V$
Reverse Recovery Time	$t_{rr}$		157		ns	$I_S=7A, V_{GS}=0V$ $di/dt=100A/\mu s$
Reverse Recovery Charge	$Q_{rr}$		1.03			

## ■ Typical Electrical and Thermal Characteristics

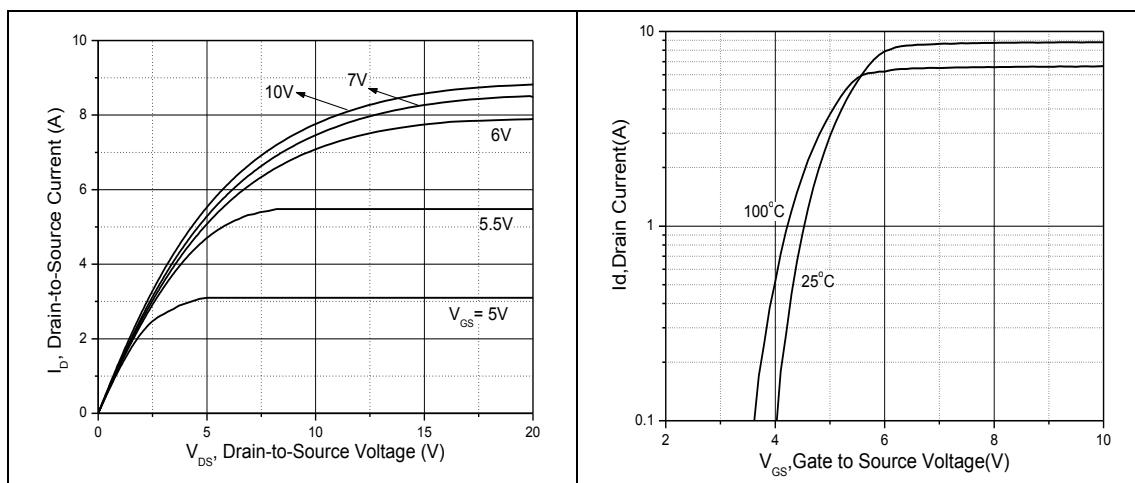


Figure 1. Typ. Output Characteristics

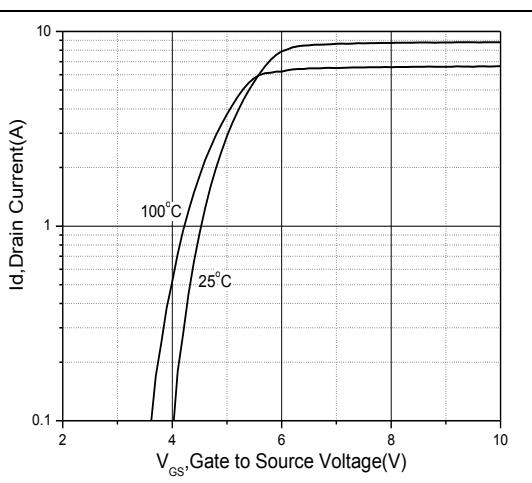


Figure 2. Transfer Characteristics

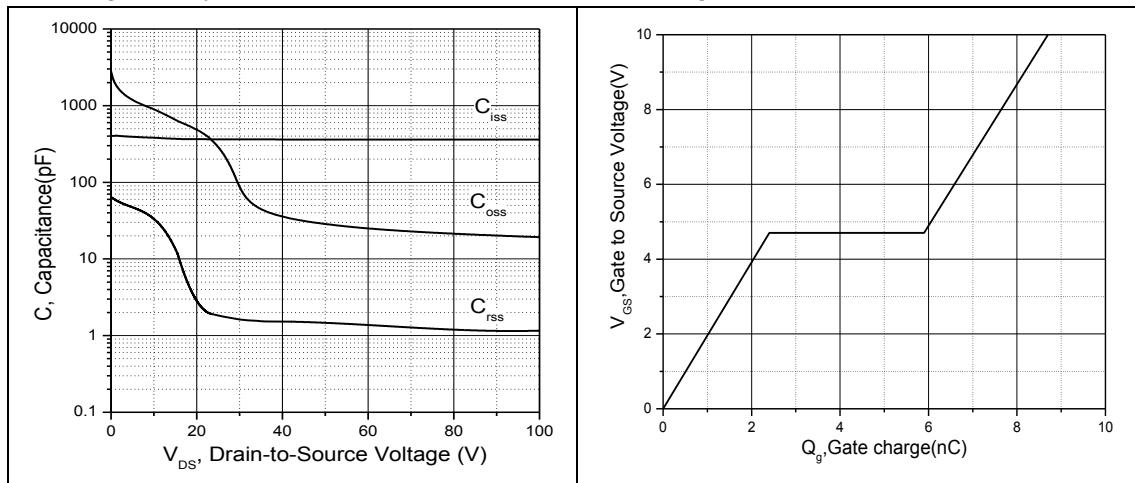


Figure 3. Typ. Capacitance

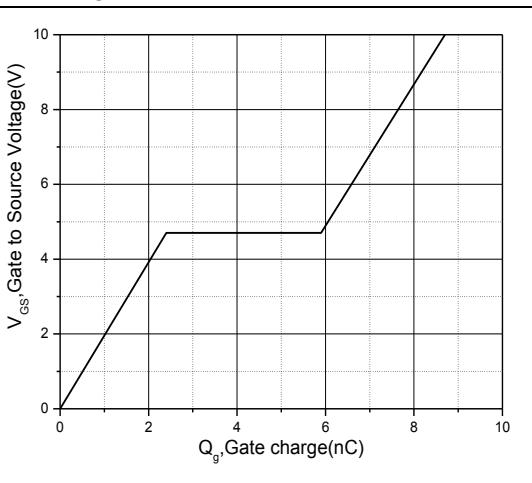


Figure 4. Gate Charge

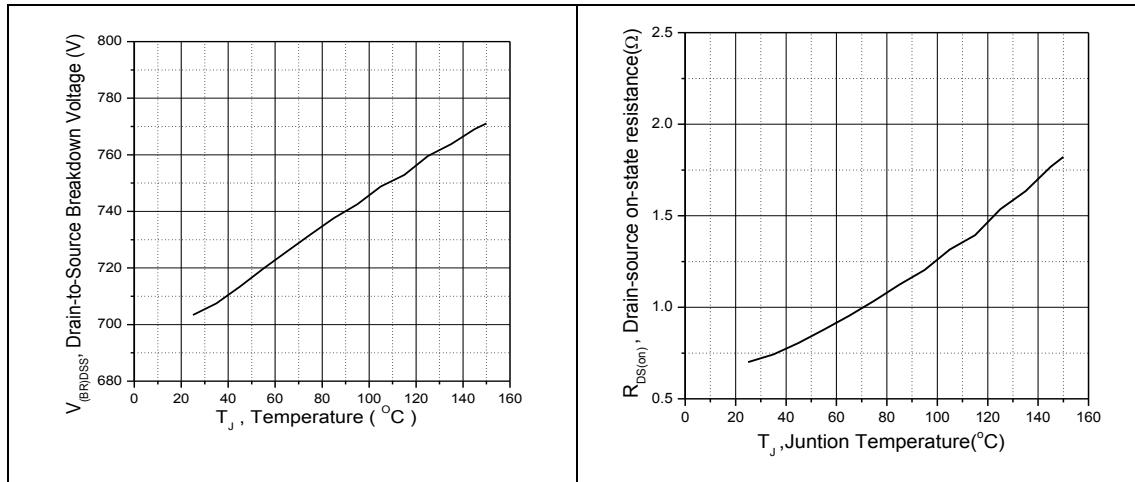


Figure 5. Drain-source breakdown voltage

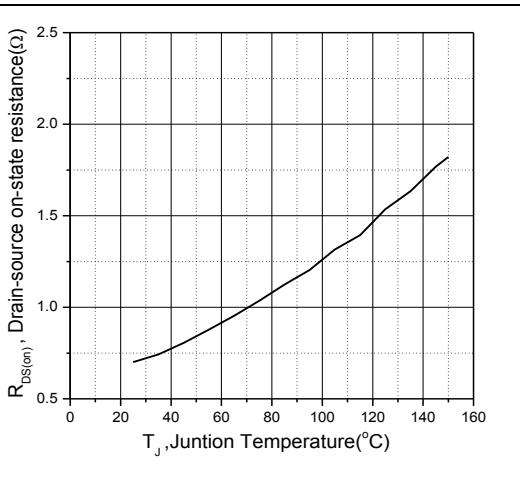
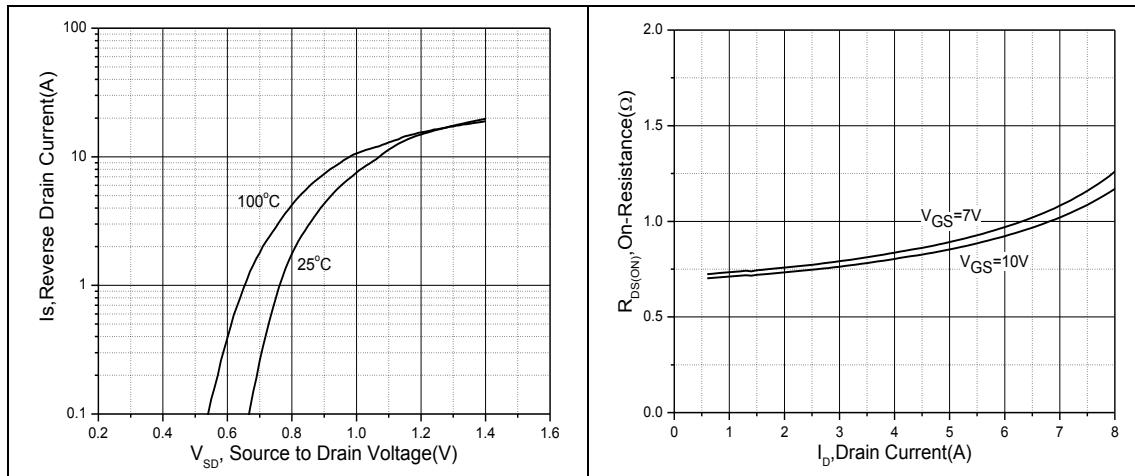
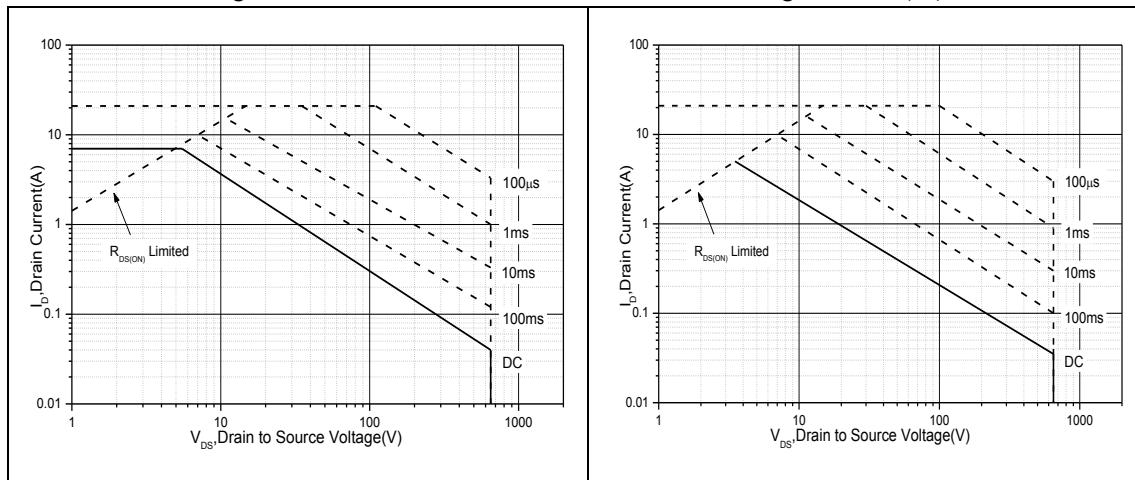


Figure 6. Drain-source on-resistance


**Figure 7.  $I_S$ - $V_{SD}$** 
**Figure 8.  $R_{DS(ON)}$ - $I_D$** 

**Figure 9. Safe Operation Area for TO251/TO252**
**Figure 10. Safe Operation Area for TO220F**

## ■ Test circuits and waveforms

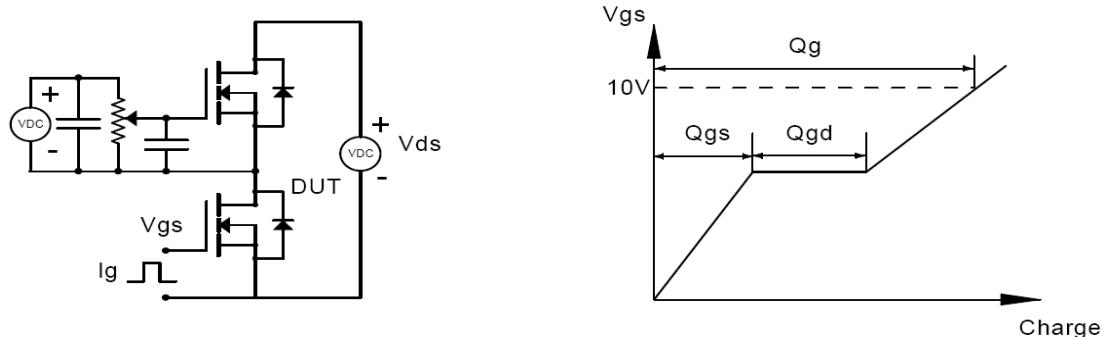


Figure 1: Gate Charge Test Circuit & Waveform

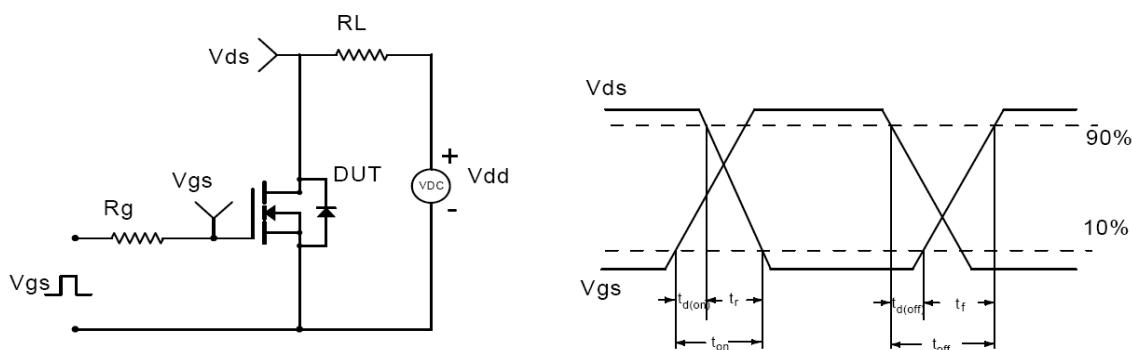


Figure 2: Resistive Switching Test Circuit & Waveforms

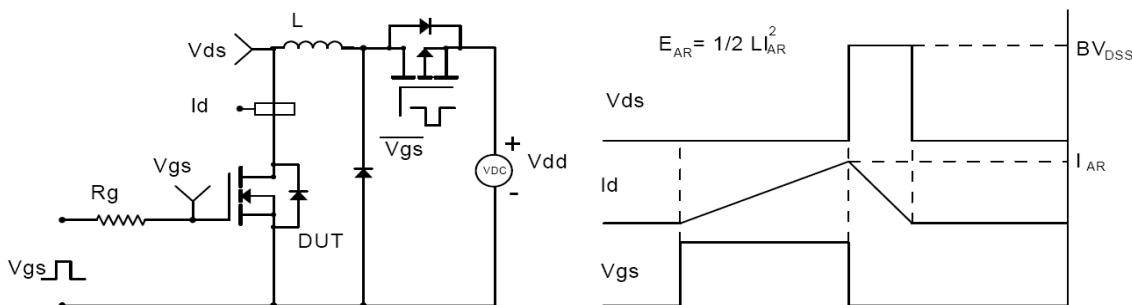


Figure 3: Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

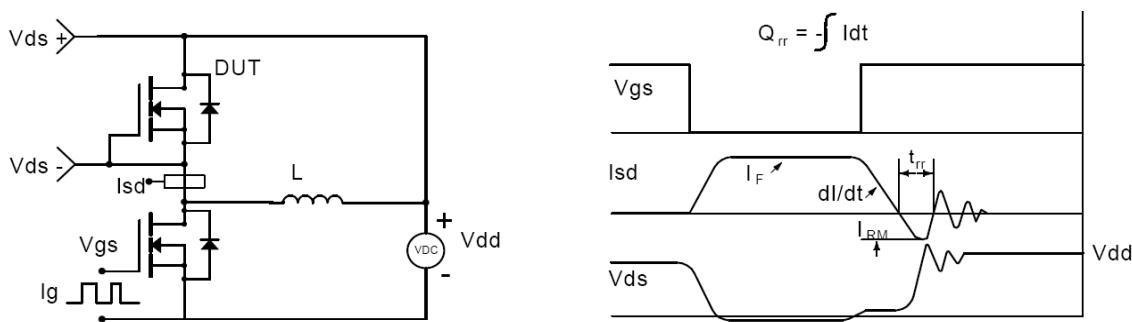
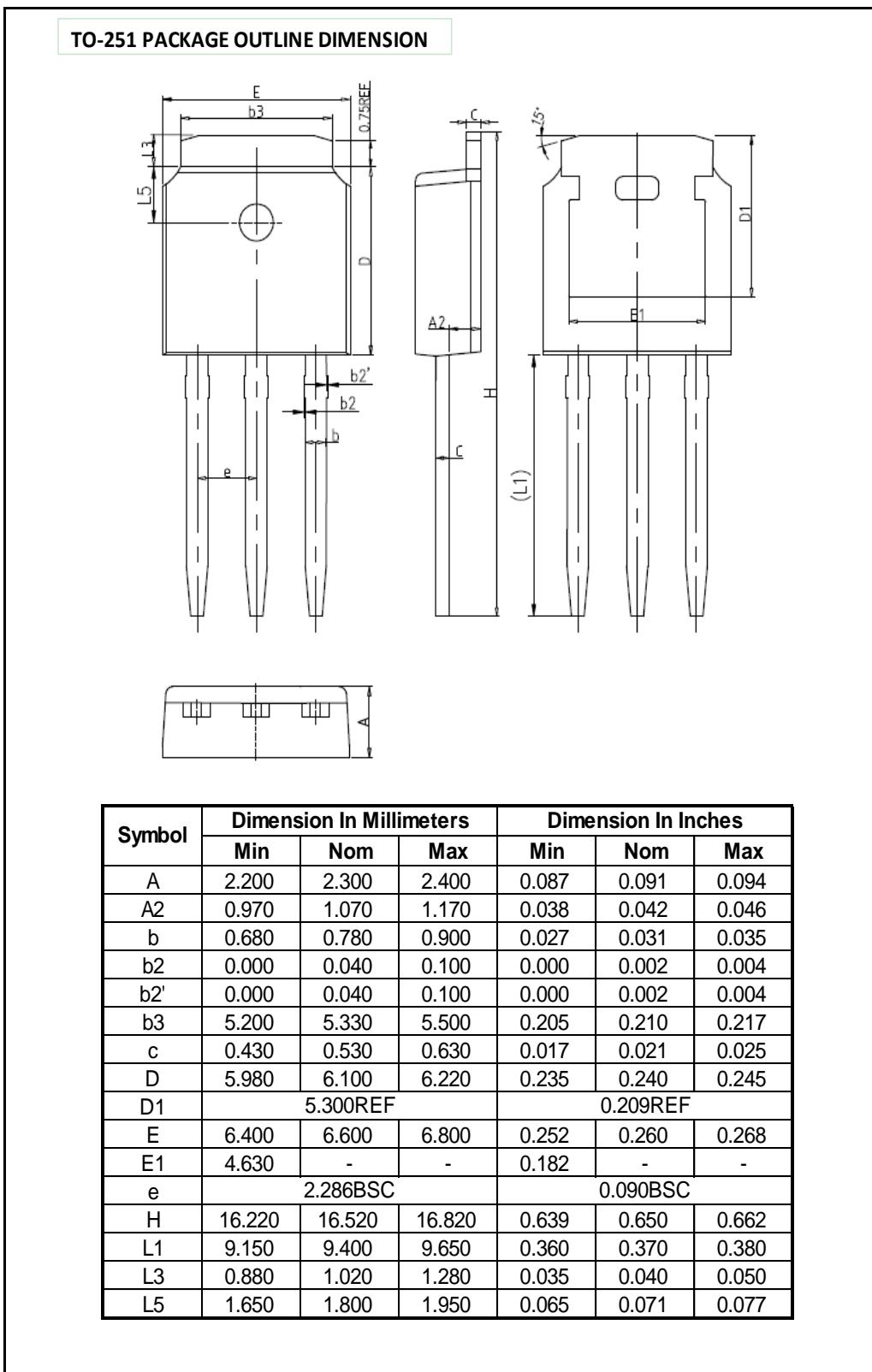


Figure 4: Diode Recovery Test Circuit & Waveforms

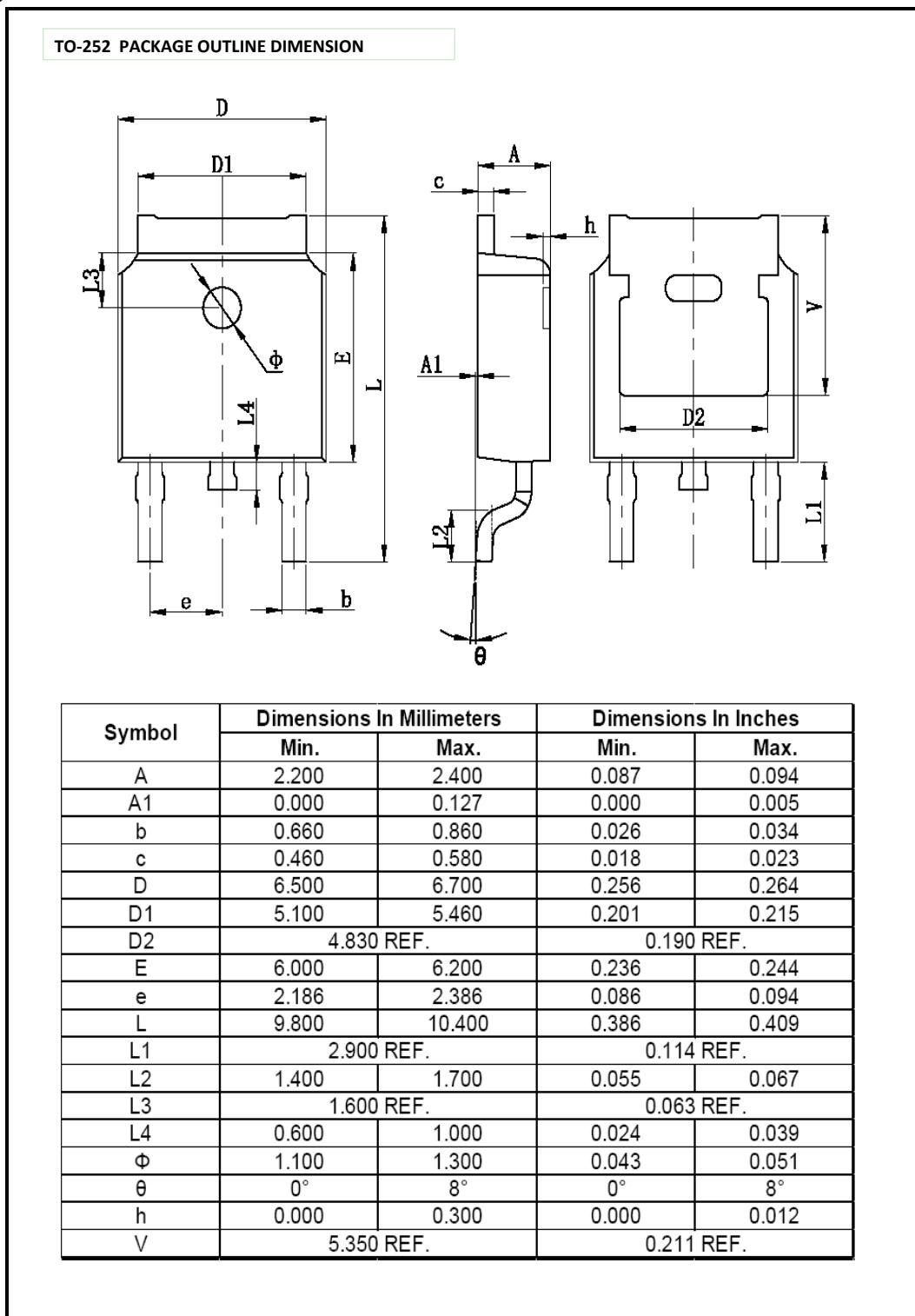
## ■ Package Information

Figure1



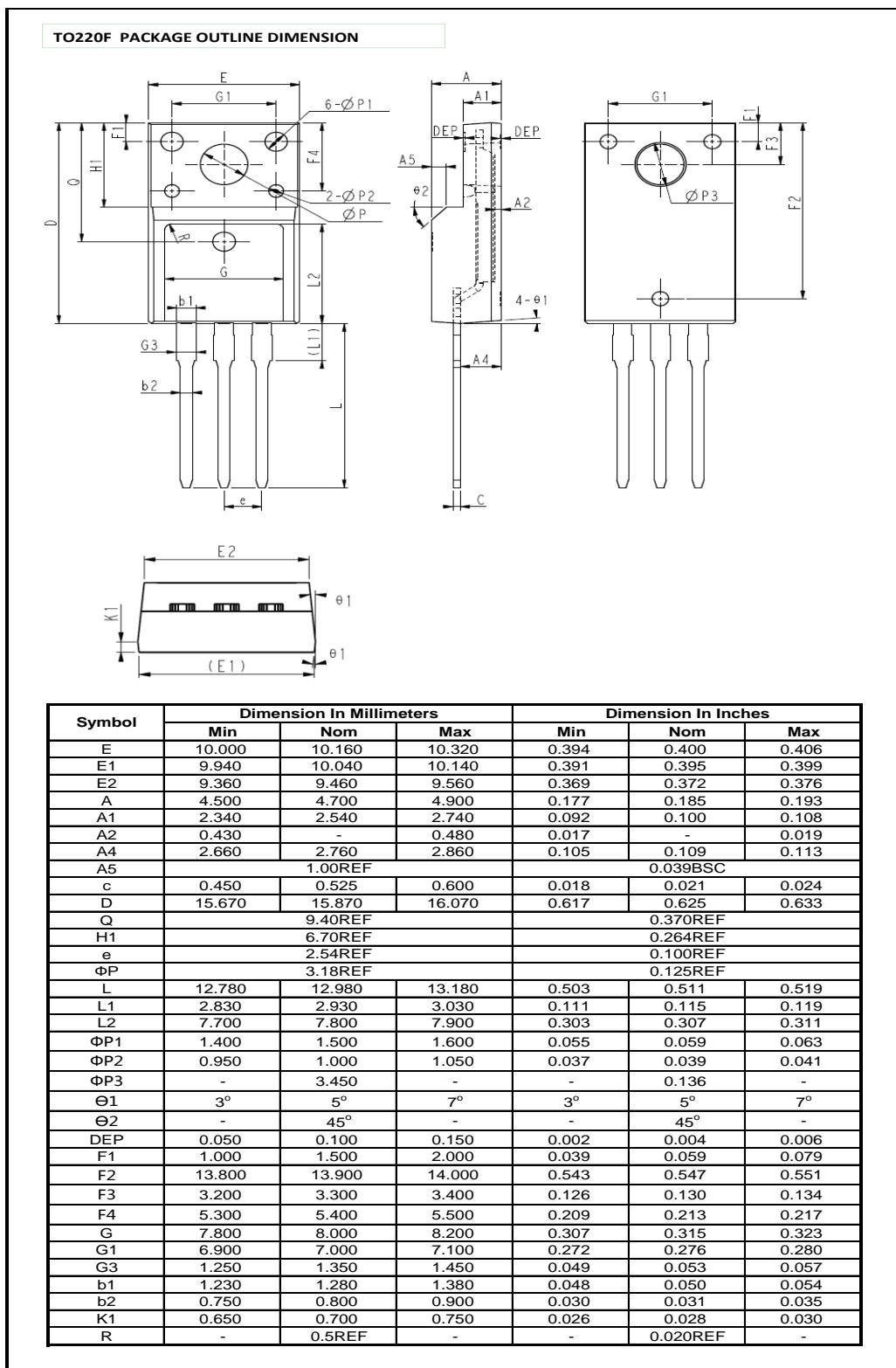
## ■ Package Information

Figure2



## ■ Package Information

Figure3



## ■ Ordering Information

Package	Units/Tape	Tapes/Inner Box	Units/Inner Box	Inner Box/Carton Box	Units/Carton Box
TO251	75	66	4950	6	29700
TO252 Option1	75	66	4950	6	29700
TO252Option2	2500	2	5000	5	25000
TO220F	50	20	1000	6	6000

## ■ Note

1. Calculated continuous current based on maximum allowable junction temperature.
2. Repetitive rating; pulse width limited by max. junction temperature.
3. PD is based on max. junction temperature, using junction-to-case thermal resistance.
4. The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ C$ .
5. Declared by design, not subject to production.
6.  $V_{DD}=50V$ ,  $R_G=25\Omega$ ,  $L=10.8mH$ , Starting  $T_J=25^\circ C$ .